

5-V Low Drop Fixed Voltage Regulator

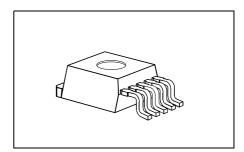
TLE 4270-2

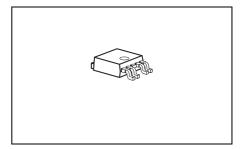




Features

- Output voltage tolerance ≤ ±2%
- 650 mA output current capability
- Low-drop voltage
- Reset functionality
- Adjustable reset time
- Suitable for use in automotive electronics
- Integrated overtemperature protection
- Reverse polarity protection
- Input voltage up to 42 V
- Overvoltage protection up to 65 V (≤ 400 ms)
- Short-circuit proof
- Wide temperature range
- ESD protection: ±2kV HBM¹⁾
- Green Product (RoHS compliant)
- AEC Qualified





Functional Description

This device is a 5-V low drop fixed-voltage regulator. The maximum input voltage is 42 V (65 V, \leq 400 ms). Up to an input voltage of 26 V and for an output current up to 650 mA it regulates the output voltage within a 2% accuracy. The short circuit protection limits the output current of more than 650 mA. The device incorporates overvoltage protection and a temperature protection which turns off the device at high temperatures.

¹⁾ ESD susceptibility, Human Body Model (HBM) according to EIA/JESD 22-A114B

Туре	Package
TLE 4270-2 G	PG-TO263-5-1
TLE 4270-2 D	PG-TO252-5-11

Data Sheet 1 Rev. 1.8, 2007-11-09



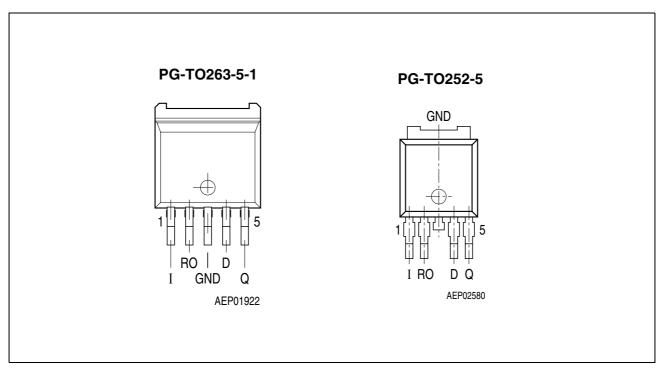


Figure 1 Pin Configuration (top view)

Table 1 Pin Definitions and Functions

Pin	Symbol	Function
1	1	Input; block to ground directly at the IC with a ceramic capacitor.
2	RO	Reset Output; the open collector output is connected to the 5-V output via an integrated resistor of 30 k Ω .
3	GND	Ground; internally connected to heatsink.
4	D	Reset Delay; connect a capacitor to ground for delay time adjustment.
5	Q	5-V Output; block to ground with 22 μF capacitor, ESR < 3 Ω .

Data Sheet 2 Rev. 1.8, 2007-11-09



Circuit Description

The control amplifier compares a reference voltage, which is kept highly accurate by resistance adjustment, to a voltage that is proportional to the output voltage and drives the base of a series transistor via a buffer. Saturation control as a function of the load current prevents any over-saturation of the power element.

The IC also incorporates a number of internal circuits for protection against:

- Overload
- Overvoltage
- Overtemperature
- Reverse polarity

Application Description

The IC regulates an input voltage in the range of 5.5 V < $V_{\rm I}$ < 36 V to $V_{\rm Q,nom}$ = 5.0 V. Up to 26 V it produces a regulated output current of more than 650 mA. Above 26 V the save-operating-area protection allows operation up to 36 V with a regulated output current of more than 300 mA. Overvoltage protection limits operation at 42 V. The overvoltage protection hysteresis restores operation if the input voltage has dropped below 36 V. A reset signal is generated for an output voltage of $V_{\rm Q}$ < 4.5 V. The delay for power-on reset can be set externally with a capacitor.

Data Sheet 3 Rev. 1.8, 2007-11-09



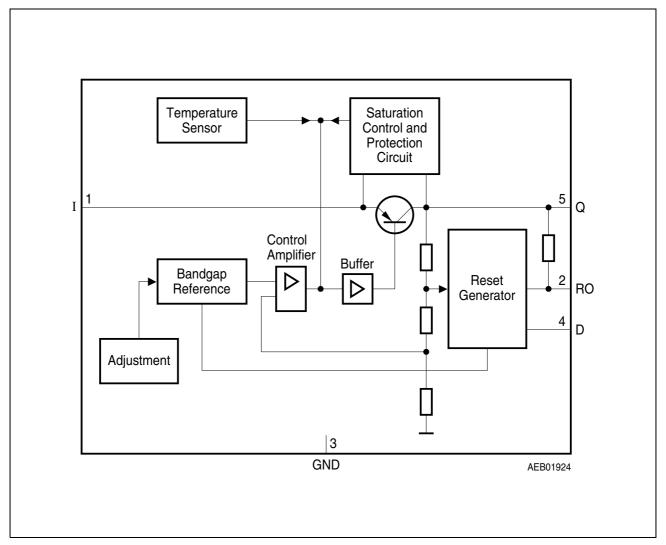


Figure 2 Block Diagram

Data Sheet 4 Rev. 1.8, 2007-11-09



Table 2 Absolute Maximum Ratings

 $T_{\rm j}$ = -40 to 150 °C

Parameter	Symbol	Lim	it Values	Unit	Notes
		Min.	Max.		
Input I	•			•	•
Voltage	V_{l}	-42	42	V	_
Voltage	V_{l}	_	65	V	<i>t</i> ≤ 400 ms
Current	I_{I}	_	_	_	internally limited
Reset Output RO	·		·	•	
Voltage	V_{RO}	-0.3	7	V	_
Current	I_{RO}	_	_	_	Internally limited
Reset Delay D					·
Voltage	V_{D}	-0.3	7	V	_
Current	I_{D}	_	_	_	Internally limited
Output Q	·		·	•	
Voltage	V_{Q}	-1.0	16	V	_
Current	I_{Q}	_	_	_	Internally limited
Ground GND					·
Current	I_{GND}	-0.5	_	А	_
Temperatures	•	•	•	•	•
Junction temperature	T_{i}	_	150	°C	_
Storage temperature	T_{stg}	-50	150	°C	_

Table 3 Operating Range

Parameter	Symbol	Lim	it Values	Unit	Notes
		Min.	Max.		
Input voltage	V_{I}	6	42	V	_
Junction temperature	$T_{\rm j}$	-40	150	°C	_
Thermal Resistance		1	1	1	
Junction ambient	$R_{\text{thj-a}}$	_	65	K/W	_
	ling a		79	K/W	TO263, TO252 ¹⁾
Junction case	R_{thj-c}	_	3	K/W	TO-263 Packages

¹⁾ Mounted on PCB, $80 \times 80 \times 1.5 \text{ mm}^3$; 35μ Cu; 5μ Sn; Footprint only; zero airflow.



 Table 4
 Characteristics

 $V_{\rm I}$ = 13.5 V; -40 °C ≤ $T_{\rm j}$ ≤ 125 °C (unless otherwise specified)

Parameter	Symbol	Limit Values			Unit	Test Condition
		Min.	Тур.	Max.	_	
Output voltage	V_{Q}	4.90	5.00	5.10	V	5 mA $\leq I_{\rm Q} \leq$ 550 mA; 6 V $\leq V_{\rm I} \leq$ 26 V
Output voltage	V_{Q}	4.90	5.00	5.10	V	26 V $\leq V_{\rm I} \leq$ 36 V; $I_{\rm Q} \leq$ 300 mA
Output current limiting	I_{Qmax}	650	850	_	mA	$V_{\rm Q}$ = 0 V
Current consumption $I_q = I_l - I_Q$	I_{q}	_	1	1.5	mA	$I_{\rm Q}$ = 5 mA
Current consumption $I_q = I_l - I_Q$	I_{q}	_	55	75	mA	$I_{\rm Q}$ = 550 mA
Current consumption $I_q = I_l - I_Q$	I_{q}	_	70	90	mA	$I_{\rm Q} = 550 \text{ mA}; V_{\rm I} = 5 \text{ V}$
Drop voltage	V_{DR}	_	350	700	mV	$I_{\rm Q} = 550 \; {\rm mA}^{1)}$
Load regulation	$\Delta V_{Q,Lo}$	_	25	50	mV	$I_{\rm Q}$ = 5 to 550 mA; $V_{\rm I}$ = 6 V
Line regulation	$\Delta V_{Q,Li}$	_	12	25	mV	$V_{\rm I}$ = 6 to 26 V $I_{\rm Q}$ = 5 mA
Power supply Ripple rejection	PSRR	_	54	_	dB	$f_{\rm r}$ = 100 Hz; $V_{\rm r}$ = 0.5 Vpp
Reset Generator						
Switching threshold	V_{RT}	4.5	4.65	4.8	V	_
Reset High voltage	V_{ROH}	4.5	-	_	V	_
Reset low voltage	V_{ROL}	_	60	_	mV	$R_{\rm int} = 30 \text{ k}\Omega^{2)};$ 1.0 V $\leq V_{\rm Q} \leq$ 4.5 V
Reset low voltage	V_{ROL}	_	200	400	mV	$I_{\rm R}$ = 3 mA, $V_{\rm Q}$ = 4.4 V
Reset pull-up	R _{int}	18	30	46	kΩ	internally connected to Q
Charge current	$I_{D,c}$	8	14	25	μΑ	$V_{\rm D}$ = 1.0 V



Table 4Characteristics (cont'd)

 $V_{\rm I}$ = 13.5 V; -40 °C ≤ $T_{\rm j}$ ≤ 125 °C (unless otherwise specified)

Parameter	Symbol Limit Values			ies	Unit	Test Condition
		Min.	Тур.	Max.		
Upper reset timing threshold	V_{DU}	1.4	1.8	2.3	V	_
Lower reset timing threshold	V_{DL}	0.2	0.45	0.8	V	$V_{\rm Q} < V_{\rm RT}$
Delay time	$t_{\sf rd}$	_	13	_	ms	$C_{\rm D}$ = 100 nF
Reset reaction time	$t_{\rm rr}$	_	_	3	μs	$C_{\rm D}$ = 100 nF
Overvoltage Protection						
Turn-Off voltage	$V_{I, ov}$	42	44	46	٧	_

¹⁾ Drop voltage = $V_{\rm l}$ - $V_{\rm Q}$ (measured when the output voltage has dropped 100 mV from the nominal value obtained at 13.5 V input)

Data Sheet 7 Rev. 1.8, 2007-11-09

²⁾ Reset peak is always lower than 1.0 V.



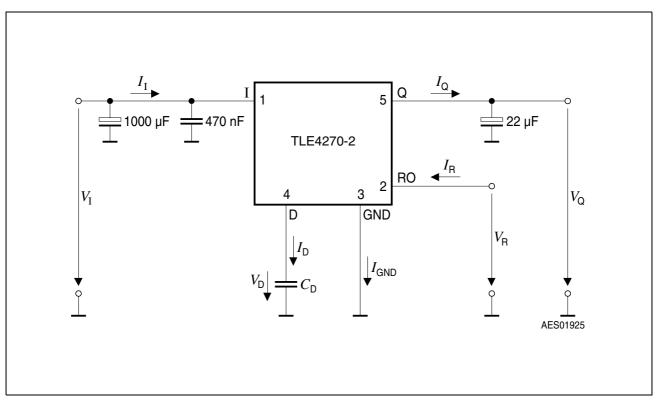


Figure 3 Test Circuit

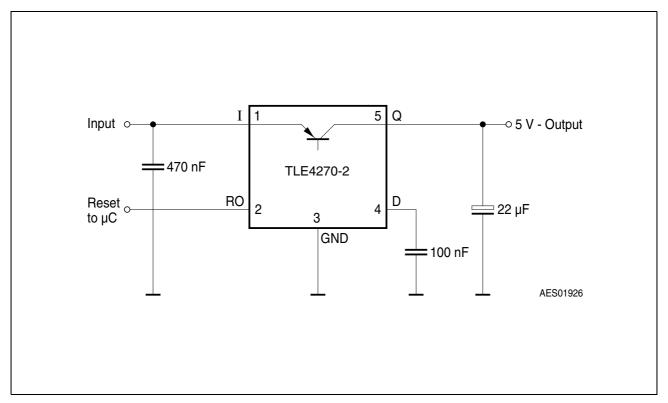


Figure 4 Application Circuit

Data Sheet 8 Rev. 1.8, 2007-11-09



Design Notes for External Components

An input capacitor $C_{\rm l}$ is necessary for compensation of line influences. The resonant circuit consisting of lead inductance and input capacitance can be damped by a resistor of approx. 1 Ω in series with $C_{\rm l}$. An output capacitor $C_{\rm Q}$ is necessary for the stability of the regulating circuit. Stability is guaranteed at values of $C_{\rm Q} \ge$ 22 $\mu \rm F$ and an ESR of < 3 Ω .

Reset Circuitry

If the output voltage decreases below 4.5 V, an external capacitor $C_{\rm D}$ on pin 4 (D) will be discharged by the reset generator. If the voltage on this capacitor drops below $V_{\rm DL}$, a reset signal is generated on pin 2 (RO), i.e. reset output is set low. If the output voltage rises above the reset threshold, $C_{\rm D}$ will be charged with constant current. After the power-on-reset time the voltage on the capacitor reaches $V_{\rm DU}$ and the reset output will be set high again. The value of the power-on-reset time can be set within a wide range depending of the capacitance of $C_{\rm D}$.

Reset Timing

The power-on reset delay time is defined by the charging time of an external capacitor C_D which can be calculated as follows:

$$C_{\rm D} = (\Delta t \times I_{\rm D.c})/\Delta V \tag{1}$$

Definitions:

- C_D = delay capacitors
- Δt = reset delay time t_{rd}
- $I_{D,c}$ = charge current, typical 14 μ A
- $\Delta V = V_{DU}$, typical 1.8 V

 $V_{\rm DU}$ = upper reset timing threshold at $C_{\rm D}$ for reset delay time

$$t_{\rm rd} = \Delta V \times C_{\rm D} / I_{\rm D.c} \tag{2}$$

The reset reaction time $t_{\rm rr}$ is the time it takes the voltage regulator to set the reset out LOW after the output voltage has dropped below the reset threshold. It is typically 1 μ s for delay capacitor of 47 nF. For other values for $C_{\rm D}$ the reaction time can be estimated using the following equation:

$$t_{\rm rr} \approx 20 \text{ s/F} \times C_{\rm D}$$
 (3)

Data Sheet 9 Rev. 1.8, 2007-11-09



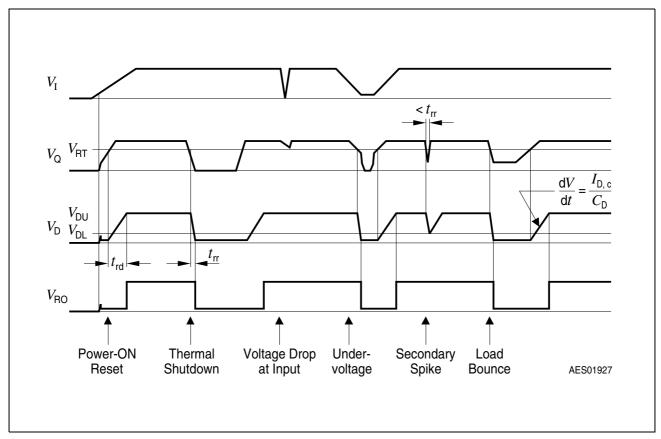
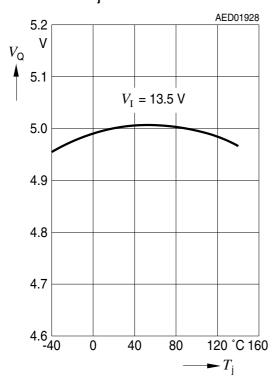


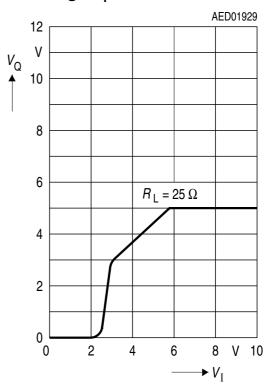
Figure 5 Reset Time Response



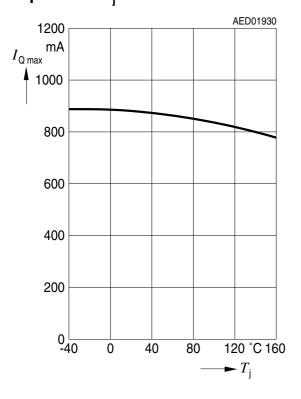
Output Voltage $V_{\rm Q}$ versus Temperature $T_{\rm i}$



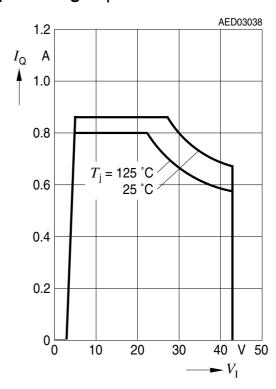
Output Voltage $V_{\rm Q}$ versus Input Voltage $V_{\rm I}$



Output Current I_{Q} versus Temperature T_{i}

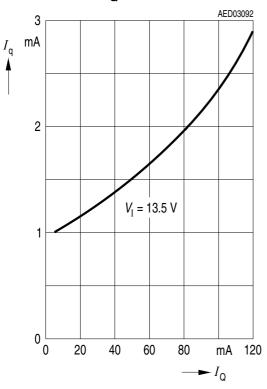


Output Current I_{Q} versus Input Voltage V_{I}

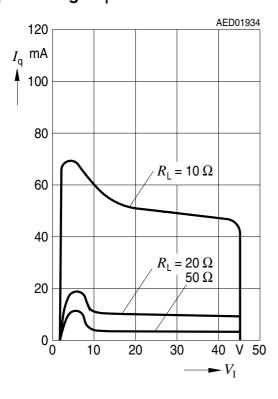




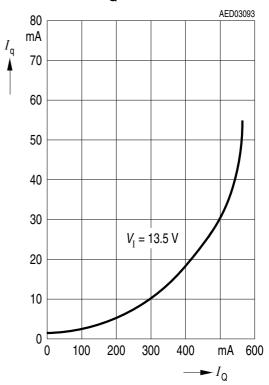
Current Consumption $I_{\rm q}$ versus Output Current $I_{\rm O}$



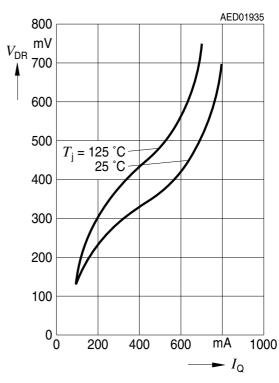
Current Consumption $I_{\rm q}$ versus Input Voltage $V_{\rm I}$



Current Consumption $I_{\rm q}$ versus Output Current $I_{\rm Q}$



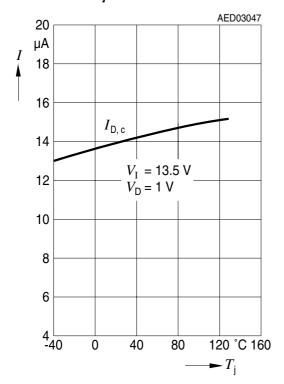
Drop Voltage V_{DR} versus Output Current I_{Q}



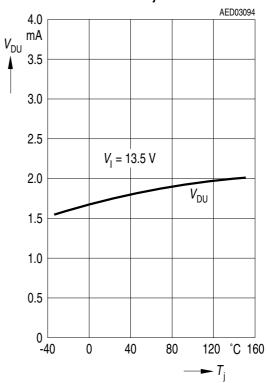
Data Sheet 12 Rev. 1.8, 2007-11-09



Charge Current $I_{\mathrm{D,c}}$ versus Temperature T_{j}



Upper Reset Timing Threshold V_{DU} versus Temperature T_{i}



Data Sheet 13 Rev. 1.8, 2007-11-09



Package Outlines

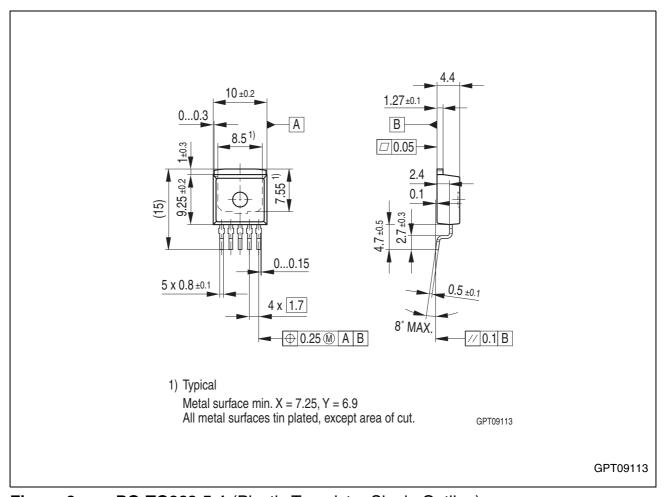


Figure 6 PG-TO263-5-1 (Plastic Transistor Single Outline)

Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

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SMD = Surface Mounted Device

Dimensions in mm



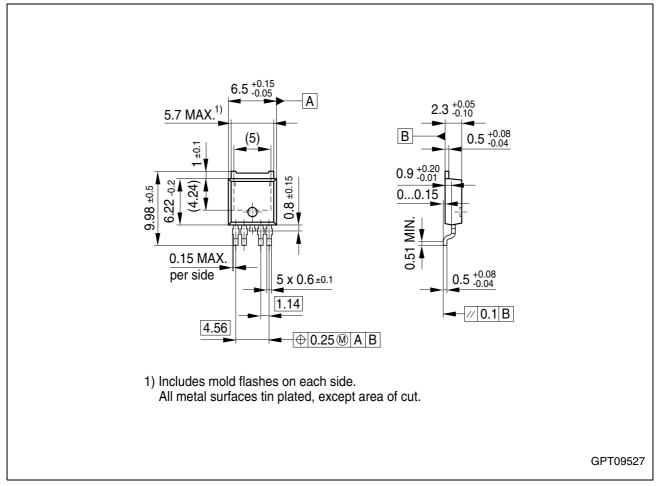


Figure 7 PG-TO252-5-11 (Plastic Transistor Single Outline)

Green Product (RoHS compliant)

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SMD = Surface Mounted Device

Dimensions in mm



Revision History

Revision History

Version	Date	Changes
Rev. 1.8	2007-11-09	Page 1: Changed ESD specification from ">4000V" to "±2kV HBM" according to PCN No. 2007-089
Rev. 1.7	2007-03-20	Initial version of RoHS-compliant derivate of TLE 4270 Change of product name to TLE 4270-2 due to modified chip layout and size. Page 1: AEC certified statement added Page 1 and Page 14: RoHS compliance statement and Green product feature added Page 1 and Page 14: Package changed to RoHS compliant version Legal Disclaimer updated

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